

## First in The Market!! Effective for Thermal Cycle Improvement /Eutectic Joint Applicable NCP (NCP:Non Conductive Paste)

### Strong Points

- 1) Eutectic Joint Applicable NCP at Higher Temperature than Normal NCP Assembly  
 (In Normal NCP, Void Appeared during Eutectic Assembly)
- 2) (In Normal NCP, Heat Press = Physical Mechanical Joint only) Dramatic Improvement of Reliability due to Eutectic Electrode Joint
- 3) Cost Down by one Process combined both of Eutectic and Encapsulation Process

### Application

- a) Flip Chip Assembly for COF, LCD Driver with Eutectic Joint  
 (Electrode Join and Underfill Layer Creation in One Process)
- b) Pre-cote Underfill Process for Eutectic Electrode Joint  
 (Joint Development with Misuzu Industries Corporation)

### Characteristic Table of New NCP

Characteristic Item		New NCP	Test Conditions
Liquid Properties	Viscosity(Pa s)	40	25°C
	Tixotropic	1.0	0.5/2.5rpm
	Gelation Time(sec)	50	150°C
	Ash content(wt%)	3.0	600°C
Cured Properties	Tg(°C)	30	TMA
	Modulus(Mpa)	500	DMA
	CTE(ppm)	60	TMA
	Impurity(ppm)	2.0	Cl ion
	Impurity(ppm)	1.2	Na ion

